AN48840B

Low current consumption, high sensitivity CMOS Hall IC Alternating magnetic field operation

(For low-speed rotation detection)

Overview

The AN48840B is a Hall ICs (a magnetic sensor) which has 2 times or more sensitivity and a low current consumption of about one fiftieth compared with our conventional one.

In this Hall IC, a Hall element, a offset cancel circuit, an amplifier circuit, a sample and hold circuit, a Schmidt circuit, and output stage FET are integrated on a single chip housed in a small package by IC technique.

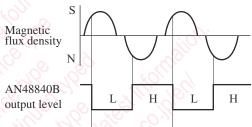
■ Features

- High sensitivity due to offset cancel circuit and a new sample and hold circuit
- Small current by using intermittent action
 (Average supply current: 56 μA typ., Sampling period: 670 μs typ.)
- Small package (SMD)
- CMOS inverter output (logic output form)

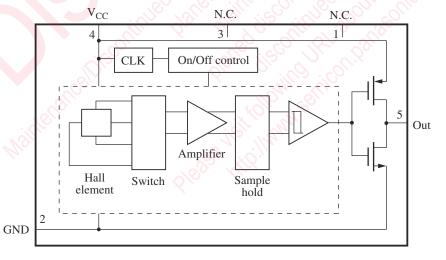
■ Applications

Functional operation key, Mouse,
 Appliances for low-speed rotation detection

0.22-0.05 (Doing plane) 0.23-0.05 (Doing plane) 0.24 (Doing plane) 0.25 (Doing plane) 0.25 (Doing plane) 0.26 (Doing plane) 0.27 (Doing plane) 0.27 (Doing plane) 0.28 (Doing plane) 0.29 (Doing plane) 0.20 (Doing plane) 0



■ Block Diagram



■ Pin Descriptions

Pin No.	Symbol	Description	Pin No.	Symbol	Description
1	N.C.	_	4	V_{CC}	Power supply
2	GND	Ground	5	Out	Output
3	N.C.	_			

■ Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	5	V
Output voltage	V _{OUT}	5	V
Supply current	I_{CC}	5	mA
Output current	I _{OUT}	15	mA
Power dissipation *1, *2	P_{D}	60	mW
Operating ambient temperature *1	T _{opr}	-25 to +75	°C
Storage temperature *1	T _{stg}	-55 to +125	°C

Note) *1: Except for the power dissipation, operating ambient temperature and storage temperature, all ratings are for T_a = 25°C.

■ Recommended Operating Range

Parameter	Symbol	Range	Unit
Supply voltage	V _{CC}	2.5 to 3.5	V

■ Electrical Characteristics $T_a = 25$ °C ± 2 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Operating magnetic flux density 1 *1	B_{HL}	$V_{CC} = 3 \text{ V}, V_{CC} = 2.5 \text{ V}$	0.5	_	6	mT
Operating magnetic flux density 2 *2	B_{LH}	$V_{CC} = 3 \text{ V}, V_{CC} = 2.5 \text{ V}$	-6	_	-0.5	mT
Output voltage 1	V_{OL1}	$V_{CC} = 3 \text{ V, } I_O = 2 \text{ mA, B} = 6.0 \text{ mT}$	_	0.1	0.3	V
Output voltage 1	V _{OL2}	$V_{CC} = 2.5 \text{ V}, I_O = 2 \text{ mA}, B = 6.0 \text{ mT}$	_	0.1	0.3	V
Output voltage 2	V_{OH1}	$V_{CC} = 3 \text{ V, } I_O = -2 \text{ mA, B} = -6.0 \text{ mT}$	2.7	2.9	_	V
Output voltage 2	V _{OH2}	$V_{CC} = 2.5 \text{ V}, I_{O} = -2 \text{ mA}, B = -6.0 \text{ mT}$	2.7	2.9	6 <u>U</u>	V
Supply current 1 *3	$I_{CC_{AVE}}$	$V_{CC} = 3 V$		56.0	85.0	μΑ
Supply current 2 *3	$I_{CC2_{AVE}}$	$V_{CC} = 2.5 \text{ V}$	4	48.0	72.0	μΑ
Intermittent action time	Tsam	$V_{CC} = 3 V$	490	670	850	μS
Intermittent action time 2	Tsam2	$V_{CC} = 2.5 \text{ V}$	513	710	890	μS

Note) *1: Symbol B_{H-LS}, B_{H-LN} stands for the operating magnetic flux density where its output level varies from high to low.

Design reference data

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Hysteresis width	BW	$V_{CC} = 3 V$	_	7	_	mT
Supply current 3	I _{CCON}	$V_{CC} = 3 V$	_	1.4	2.1	mA
Supply current 4	I_{CCOFF}	$V_{CC} = 3 V$	_	2.5	_	μΑ
Supply current 5	I _{CC2ON}	$V_{CC} = 2.5 \text{ V}$	_	1.12	1.68	mA
Supply current 6	I _{CC2OFF}	$V_{CC} = 2.5 \text{ V}$	_	2.2	_	μА
Operating time	t _{ON}	$T_a = -25$ °C to 75°C, $V_{CC} = 3$ V	10	26	42	μS
Stop time	t _{OFF}	$T_a = -25$ °C to 75°C, $V_{CC} = 3$ V	258	644	1 030	μS
Operating time 2	t _{2ON}	$T_a = -25$ °C to 75°C, $V_{CC} = 2.5$ V	11	27	43	μS
Stop time 2	t _{2OFF}	$T_a = -25$ °C to 75°C, $V_{CC} = 2.5$ V	270	674	1 078	μS

Note) It will operate normally in approximately 0.67 ms after power on.

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^{*2:}T_a = 75°C. For the independent IC without a heat sink. Please use within the range of power dissipation, refering to P_D — T_a curve.

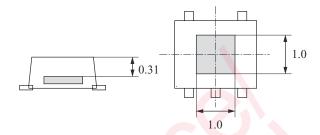
^{*2}:Symbol $B_{L\text{-HS}}$, $B_{L\text{-HN}}$ stands for the operating magnetic flux density where its output level varies from low to high.

 $^{*3:}I_{\text{CC}_{\text{AVE}}} = \{I_{\text{CC}_{\text{ON}}} \times t_{\text{ON}} + I_{\text{CC}_{\text{OFF}}} \times t_{\text{OFF}}\} / \{t_{\text{ON}} + t_{\text{OFF}}\}$

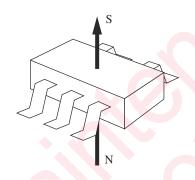
■ Technical Data

• Position of a Hall element (unit in mm)

Distance from a package surface to sensor part: 0.31 mm (reference value) A Hall element is placed on the shaded part in the figure.



• Magneto-electro conversion characteristics



Output voltage

BLH

BW

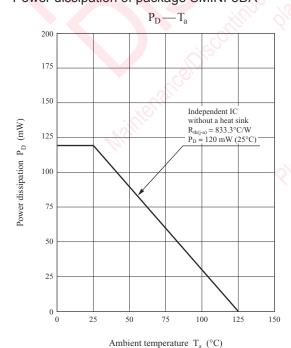
BHL

Applied magnetic flux density B

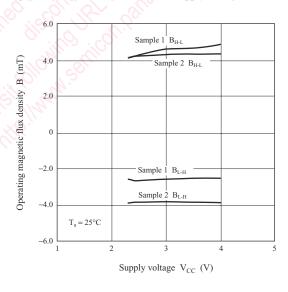
Direction of applied magnetic field

Operating magnetic flux density

Power dissipation of package SMINI-5DA



AN48840B Main characterisitcs
 Operating magnetic flux density — Supply voltage



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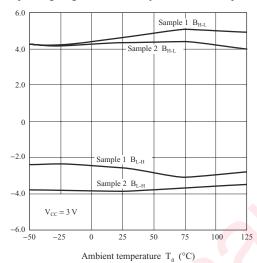
Panasonic

Supply current I_{CC} (µA)

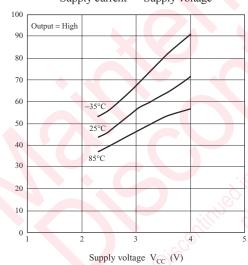
■ Technical Data (continued)

• AN48840B Main characterisitcs (continued)

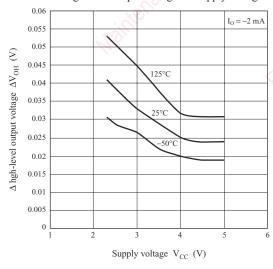
Operating magnetic flux density — Ambient temperature



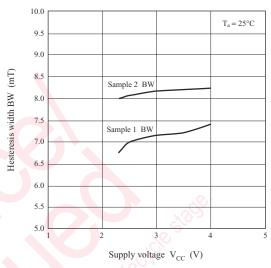
Supply current — Supply voltage



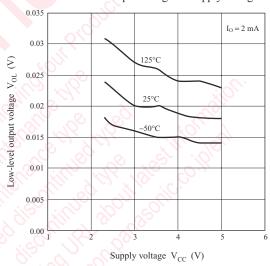
Δ high-level output voltage — Supply voltage



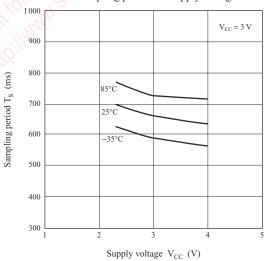
Hysteresis width — Supply voltage



Low-level output voltage — Supply voltage



Sampling period — Supply voltage



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